

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Shinsuke TAKEOKA	09/28/2007
RECEIVING PARTY DATA	
Name:	Taiyo Yuden Co., Ltd.
Street Address:	16-20, Ueno 6-chome, Taito-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	110-0005
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11854661
CORRESPONDENCE DATA	
Fax Number:	(949)760-9502
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	949 760 0404
Email:	efiling@kmob.com
Correspondent Name:	Knobbe Martens Olson & Bear, LLP
Address Line 1:	2040 Main Street
Address Line 4:	Irvine, CALIFORNIA 92614
ATTORNEY DOCKET NUMBER:	TAYU.113AUS
NAME OF SUBMITTER:	Katsuhiro Arai
Total Attachments: 1 source=Assignment_TAYU-113AUS#page1.tif	

CH 11854661 \$40.00

500388727

PATENT
REEL: 020050 FRAME: 0496

ASSIGNMENT

WHEREAS, I, Shinsuke TAKEOKA, a Japanese citizen, residing at Gunma, Japan, have invented certain new and useful improvements in MULTI-LAYER CERAMIC CAPACITOR which we have executed an application for Letters Patent in the United States, on September 13, 2007 as Application Serial No. 11/854,661;

AND WHEREAS, Taiyo Yuden Co., Ltd., a Japanese Corporation, with its principal place of business at 16-20, Ueno 6-chome, Taito-ku, Tokyo 110-0005 Japan (hereinafter "ASSIGNEE"), desire to acquire the right, title, and interest in and to the said improvements and the said Application, so that the right, title, and interest in and to the said improvements and the said Application are owned by the said ASSIGNEE;

NOW, THEREFORE, in return for good and valuable consideration, the receipt of which is hereby acknowledged, Assignor hereby acknowledge that I have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the ASSIGNEE, its successors, legal representatives and assigns, the right, title, and interest throughout the world in, to and under the said improvements, and the said application and all provisional applications relating thereto, and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions and applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and I hereby authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I HEREBY covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

This 28 day of September, 2007

Shinsuke Takeoka
Shinsuke TAKEOKA

Nobuo Yokomura
Witness